

1. MODEL NUMBER

MODEL NUMBER.	CUSTOMER PART NO.
BP65R765S112	

2. TEST CONDITION

2-1 TYPICAL CONDITION : -TEMPERATURE : 20℃

-HUMIDITY : 65%RH

2-2 STANDARD CONDITION : -TEMPERATURE : -40℃ to +85℃


-HUMIDITY : 45%RH to 85%RH

3. COMPOSITION AND MATERIAL

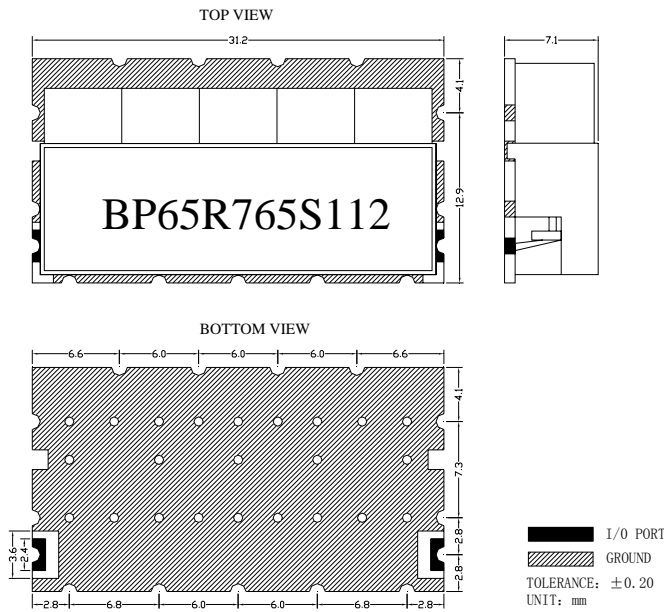
NO.	NAME	COMPOSITION AND MATERIALS
3-1	RESONATOR	DIELECTRIC MATERIALS
3-2	NUMBER OF POLE	5 POLE
3-3	IN/OUTPUT TERMINALS	Ag or Sn PLATED
3-4	GROUND BASE	Ag or Sn PLATED

4. ELECTRICAL SPECIFICATIONS

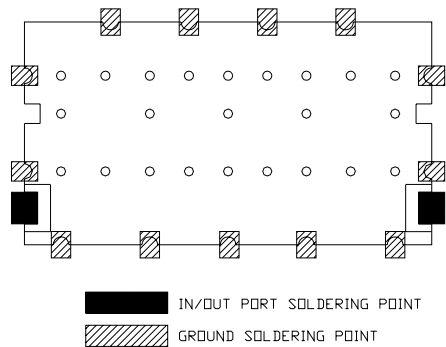
NO.	ITEM	SPECIFICATIONS
4-1	CENTER FREQUENCY(f_0)	765.0MHz
4-2	BAND WIDTH	± 56.0 MHz
4-3	INSERTION LOSS IN BW	2.5dB max.
4-4	RIPPLE	1.0dB max.
4-5	RETURN LOSS	14dB min.
4-6	ATTENUATION	30dBc min. at 637MHz and 952MHz
4-7	INPUT POWER	1 W
4-8	NOMINAL CHARACTERISIC IMPEDANCE	50 Ω

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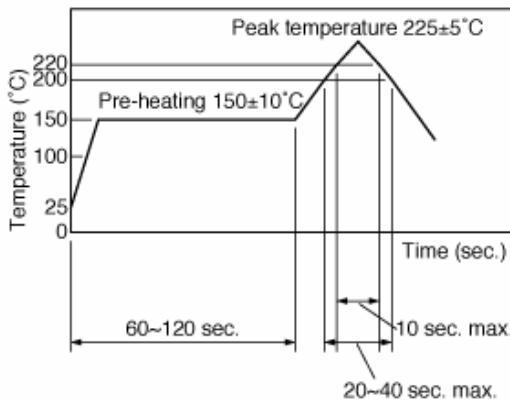
5. DIMENSIONS



6. RECOMMENDED REFLOW PAD

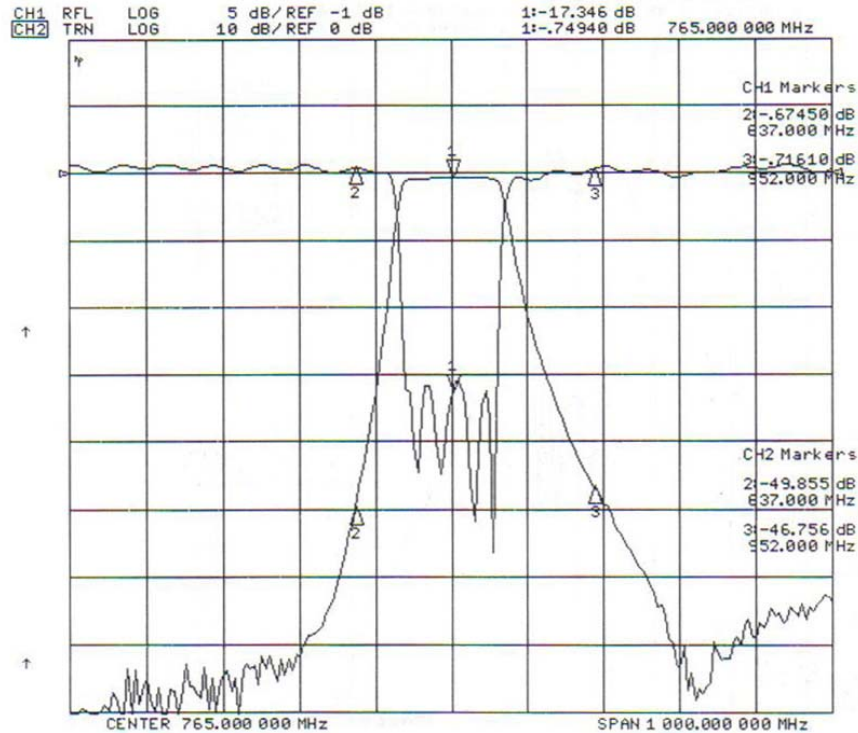
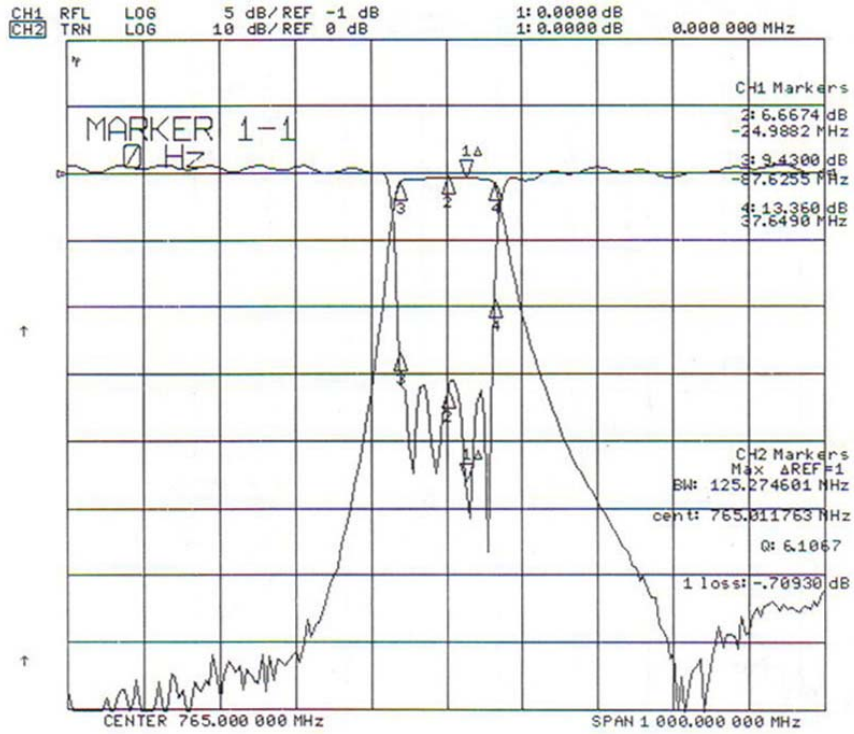


7. REFLOW SOLDERING STANDARD CONDITIONS



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8.CHARACTERISTICS



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